



RS4-M Material Safety Data Sheet

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Wire 30.84%	Copper (Cu)	7440-50-8	1,236.49	99.97671	308,244.1
	Phosphorus (P)	7723-14-0	0.014	0.00109	3.5
	Arsenic (As)	7440-38-2	0.014	0.00109	3.5
	Tin (Sn)	7440-31-5	0.014	0.00109	3.5
	Oxygen (O)	7782-44-7	0.007	0.00055	1.7
	Sulfur (S)	7704-34-9	0.162	0.01314	40.4
	Iron (Fe)	7439-89-6	0.009	0.00072	2.2
	Nickel (Ni)	7440-02-0	0.004	0.00034	1.0
	Bismuth (Bi)	7440-69-9	0.027	0.00219	6.7
	Antimony (Sb)	1309-64-4	0.027	0.00219	6.7
	Lead (Pb)	7439-92-1	0.027	0.00055	6.7
	Zinc (Zn)	7440-66-6	0.004	0.00034	1.0
	Total		1,236.80		
Solder Wafer 0.48%	Lead (Pb)	7439-92-1	17.93	91.85	4,469.8
	Tin (Sn)	7440-31-5	1.06	5.43	264.2
	Silver (Ag)	7440-22-4	0.53	2.72	132.1
	Total		19.52		
Chip 0.21%	Silicon (Si)	7440-21-3	6.1910	95.40	1,543.4
	Lead (Pb)	7439-92-1	0.2990	4.60	74.5
	Total		6.49		
Molding 68.29%	Silica (SiO ₂)	14808-60-7	2000.93	73.00	498,573.5
	Epoxy resin	29690-82-2	466.03	17.00	116,121.1
	Phenolic resin	9003-35-4	241.24	8.80	60,101.0
	Antimony trioxide(Sb ₂ O ₃)	1309-64-4	19.19	0.70	4,781.6
	Brominated epoxy resin	40039-93-8	12.61	0.46	3,142.0
	Carbon Black	1333-86-4	1.36	0.04	338.8
	Total		2,741.36		
Plating 0.18%	Tin (Sn)	7440-31-5	7.23	100.00	1,802.4
	Total		7.23		
	Total mass		4,011.40		